

## AMENDMENTS TO CLAIMS

**Claim 1 (Currently Amended)** A method for manufacturing a printed wiring board, ~~including the steps of: board which includes~~ forming a thermosetting resin layer so as to fill spaces between circuit patterns formed on a surface of the printed wiring board, ~~board;~~ heating and curing the resin layer, ~~layer,~~ and then polishing ~~said the~~ cured resin layer covering ~~said the~~ circuit patterns, thereby exposing ~~said the~~ circuit patterns, wherein ~~said the~~ step of heating and curing ~~said the~~ resin layer comprises ~~the following steps:~~

maintaining ~~said the~~ resin layer at a non-curable temperature where ~~said the~~ resin layer is pressed via a smoothing plate in a reduced pressure environment (~~step 1~~);

heating ~~said the~~ resin layer in ~~said the~~ pressed state to a curing temperature at which ~~said the~~ resin layer is cured (~~step 2~~);

introducing outside air ~~to eliminate into the~~ reduced pressure environment while maintaining ~~said the~~ pressed state and ~~said the~~ curing temperature (~~step 3~~);

reducing the pressure applied to ~~said the~~ smoothing plate while maintaining ~~said the~~ curing temperature (~~step 4~~); and

cooling ~~said the~~ resin layer (~~step 5~~).

**Claim 2 (Currently Amended)** The method for manufacturing a printed wiring board according to claim 1, wherein ~~in said step 1 the~~ an applied pressure ~~of to~~ the smoothing plate is increased in predetermined steps.

**Claim 3 (Currently Amended)** The method for manufacturing a printed wiring board according to claim 2, wherein ~~said the~~ resin layer is formed by ~~adhereing~~ adhering a liquid resin to ~~said the~~ printed wiring board so as to fill spaces between ~~said the~~ circuit patterns, and wherein a metallic foil with a roughened surface facing ~~said the~~ resin layer is superposed on the resin layer.

**Claim 4 (Currently Amended)** The method for manufacturing a printed wiring board

according to claim 1, wherein ~~said~~the resin layer is formed by superposing a semi-cured resin sheet on the printed wiring board, and wherein a metallic foil with a roughened surface facing ~~said~~the resin layer is superposed on the resin layer.

**Claim 5 (Currently Amended)** The method for manufacturing a printed wiring board according to claim 3, wherein ~~said~~the metallic foil is formed with a different type of metal than ~~said~~the circuit patterns.

**Claim 6 (Currently Amended)** The method for manufacturing a printed wiring board according to claim 4, wherein ~~said~~the metallic foil is formed with a different type of metal than ~~said~~the circuit patterns.

**Claim 7 (Currently Amended)** The method for manufacturing a printed wiring board according to claim 1 wherein ~~said~~the reduced pressure environment is provided by a reduced pressure chamber.

**Claim 8 (Currently Amended)** The method for manufacturing a printed wiring board according to claim 1, wherein ~~said~~the resin layer is formed by adhering a liquid resin to ~~said~~the printed wiring board so as to fill spaces between ~~said~~the circuit patterns, and wherein a metallic foil with a roughened surface facing ~~said~~the resin layer is superposed on the resin layer.

**Claim 9 (Currently Amended)** The method for manufacturing a printed wiring board according to claim 8, wherein ~~said~~the metallic foil is formed with a different type of metal than ~~said~~the circuit patterns.

**Claim 10 (Currently Amended)** The method for manufacturing a printed wiring board according to claim 2, wherein ~~said~~the resin layer is formed by superposing a semi-cured resin sheet on the printed wiring board, and wherein a metallic foil with a roughened surface facing

~~said~~the resin layer is superposed on the resin layer.

**Claim 11 (Currently Amended)** The method for manufacturing a printed wiring board according to claim 10, wherein ~~said~~the metallic foil is formed with a different type of metal than ~~said~~the circuit patterns.

**Claims 12-19 (Canceled)**